

AMENDMENTS TO THE CLAIMS

1. (Withdrawn)
2. (Withdrawn)
3. (Withdrawn)
4. (Withdrawn))
5. (Withdrawn)
6. (Withdrawn)
7. (Withdrawn)
8. (Withdrawn)
9. (Withdrawn)
10. (Withdrawn)
11. (Currently Amended) An apparatus having a sealed open microchannel therein, comprising:
 - an etched substrate,
 - an etched open microchannel in said etched substrate,
 - an annealed substrate positioned on said etched substrate that covers said etched microchannel in said etched substrate,
 - an annealed open microchannel that has been produced by annealing in said annealed substrate covering said etched microchannel in said etched substrate, and
 - a bond connecting said etched substrate and said annealed substrate,wherein said etched open microchannel and said annealed open microchannel comprise said sealed open microchannel.
12. (Currently Amended) The apparatus of Claim 11, wherein said annealed microchannel is a high temperature annealed microchannel annealed in the 600° to 800° range.

13. (Currently Amended) The apparatus of Claim 11, wherein said etched microchannel in said etched substrate and said microchannel in said annealed substrate form a circular microchannel.

14. (Currently Amended) The apparatus of Claim 11, wherein said etched substrate and said annealed substrate are selected from the group consisting of glass members, glass and silicon members, glass and polymer members, and members selected from the group of glass, silicon and polymers.

15. (Previously Amended) The apparatus of Claim 11, wherein said bond comprises fusion or anodic bonding.

16. (Currently Amended) The apparatus of Claim 11, wherein said annealed microchannel has depth of about 10 μm and a width of about 20 μm and said annealed microchannel is a high temperature annealed microchannel annealed in the 600° to 800° range.